

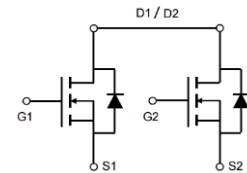
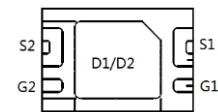
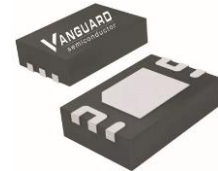
Features

- Dual N-Channel, 2.5V Logic Level Control
- Enhancement mode
- Low on-resistance $R_{DS(on)}$ @ $V_{GS}=2.5V$
- 100% Avalanche Tested
- Pb-free lead plating; RoHS compliant



Part ID	Package Type	Marking	Tape and reel information
VSA007N02KD	TDFN2x3-6L	7N02	3000pcs/Reel

V_{DS}	20	V
$R_{DS(on),TYP} @ V_{GS}=4.5V$	7.4	m Ω
$R_{DS(on),TYP} @ V_{GS}=2.5V$	9.4	m Ω
I_D	13	A

TDFN2x3-6L


Maximum ratings, at $T_j=25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	20	V
I_S	Diode continuous forward current	$T_A=25^\circ\text{C}$ 13	A
I_D	Continuous drain current	$T_A=25^\circ\text{C}$ 13	A
		$T_A=100^\circ\text{C}$ 8.2	A
I_{DM}	Pulse drain current tested ①	$T_A=25^\circ\text{C}$ 52	A
EAS	Avalanche energy, single pulsed ②	12	mJ
P_D	Maximum power dissipation	$T_A=25^\circ\text{C}$ 2	W
V_{GS}	Gate-Source voltage	± 12	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance: Junction to Case	45	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance: Junction to Ambient	62.5	$^\circ\text{C/W}$



Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
Static Electrical Characteristics @ T_c = 25°C (unless otherwise stated)						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current(T _c =25°C)	V _{DS} =20V, V _{GS} =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T _c =125°C)	V _{DS} =20V, V _{GS} =0V	--	--	100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V	--	--	±100	nA
V _{GS(TH)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.4	0.7	1.0	V
R _{DS(ON)}	Drain-Source On-State Resistance ^③	V _{GS} =4.5V, I _D =5A	--	7.4	10	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance ^③	V _{GS} =3.3V, I _D =4A	--	8.1	11	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance ^③	V _{GS} =2.5V, I _D =3A	--	9.4	12	mΩ
Dynamic Electrical Characteristics @ T_c = 25°C (unless otherwise stated)						
C _{iss}	Input Capacitance	V _{DS} =10V, V _{GS} =0V, f=1MHz	1000	1225	1450	pF
C _{oss}	Output Capacitance		130	200	270	pF
C _{rss}	Reverse Transfer Capacitance		100	170	240	pF
R _g	Gate Resistance	f=1MHz	--	2.2	--	Ω
Q _g	Total Gate Charge	V _{DS} =10V, I _D =5A, V _{GS} =4.5V	--	15	--	nC
Q _{gs}	Gate-Source Charge		--	6	--	nC
Q _{gd}	Gate-Drain Charge		--	7	--	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DD} =10V, I _D =5A, R _G =3Ω, V _{GS} =4.5V	--	3.2	--	nS
t _r	Turn-on Rise Time		--	4.6	--	nS
t _{d(off)}	Turn-Off Delay Time		--	9	--	nS
t _f	Turn-Off Fall Time		--	9.4	--	nS
Source- Drain Diode Characteristics @ T_c = 25°C (unless otherwise stated)						
V _{SD}	Forward on voltage	I _{SD} =5A, V _{GS} =0V	--	0.7	1.2	V
t _{rr}	Reverse Recovery Time	T _j =25°C, I _{sd} =5A, V _{GS} =0V	--	13	--	nS
Q _{rr}	Reverse Recovery Charge	di/dt=500A/μs		17		nC

NOTE:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Limited by T_{Jmax}, starting T_J = 25°C, L = 0.1mH, R_G = 25Ω, I_{AS} = 12A, V_{GS} = 4.5V. Part not recommended for use above this value
- ③ Pulse width ≤ 300μs; duty cycle ≤ 2%.

Typical Characteristics

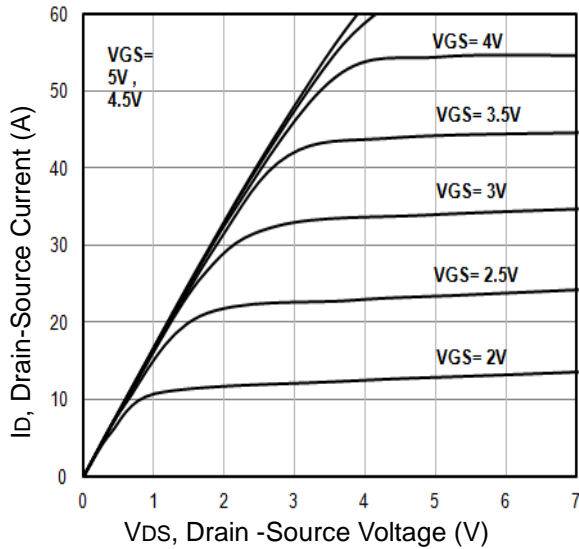


Fig1. Typical Output Characteristics

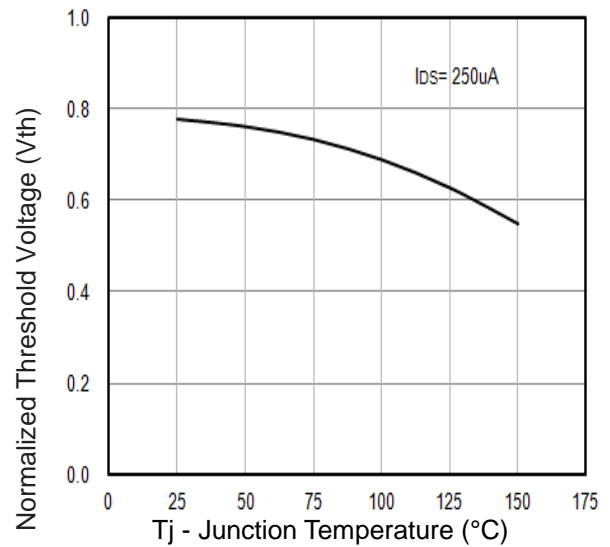


Fig2. Normalized Threshold Voltage Vs. Temperature

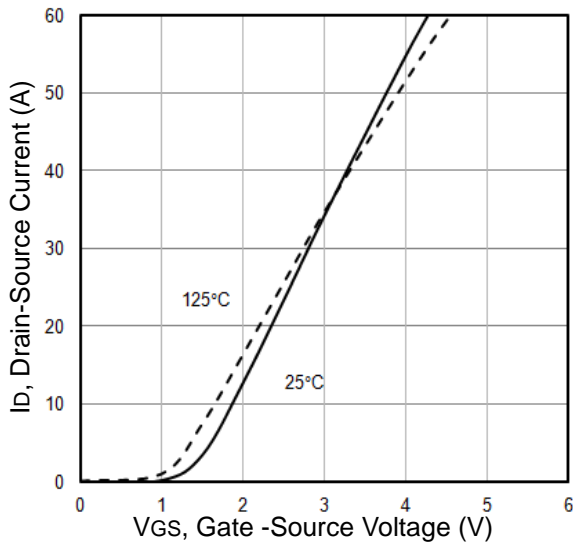


Fig3. Typical Transfer Characteristics

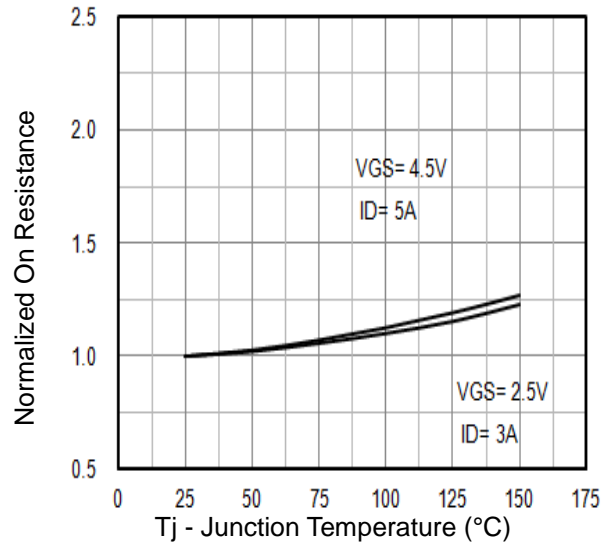


Fig4. Normalized On-Resistance Vs. Temperature

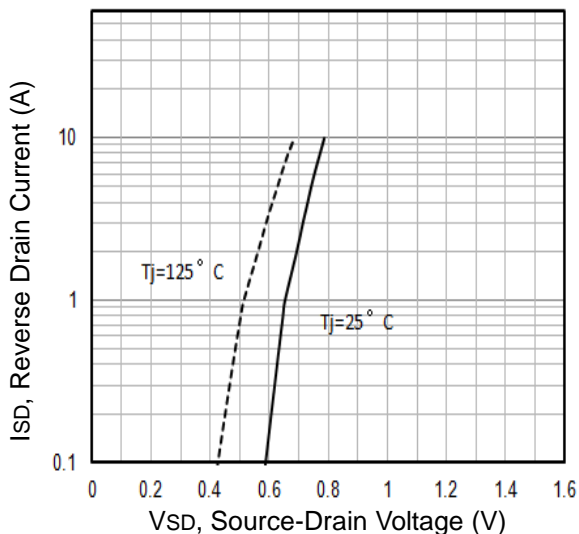


Fig5. Typical Source-Drain Diode Forward Voltage

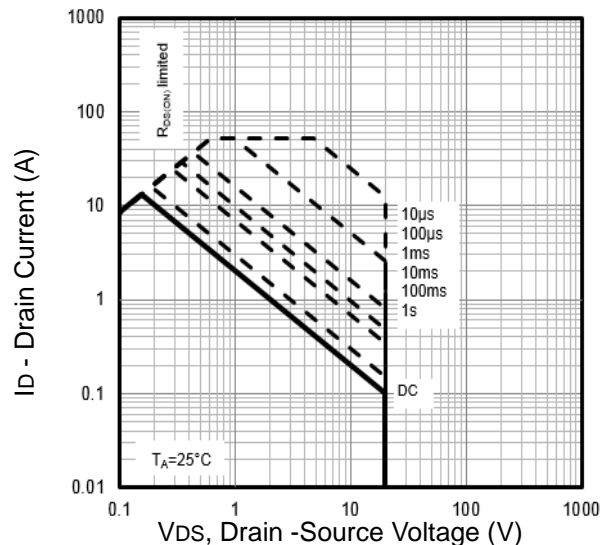


Fig6. Maximum Safe Operating Area



Typical Characteristics

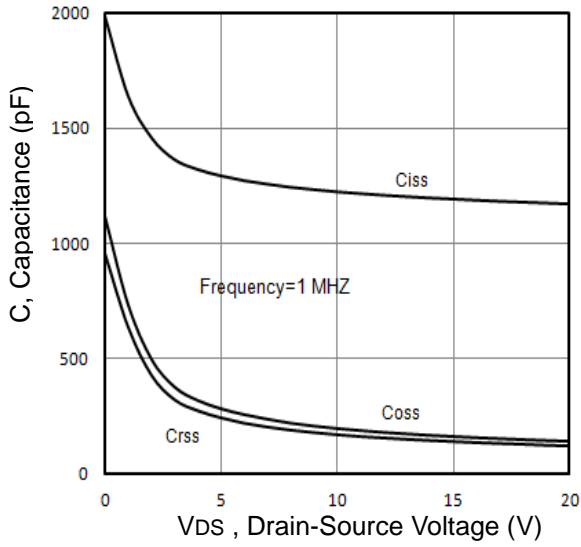


Fig7. Typical Capacitance Vs. Drain-Source Voltage

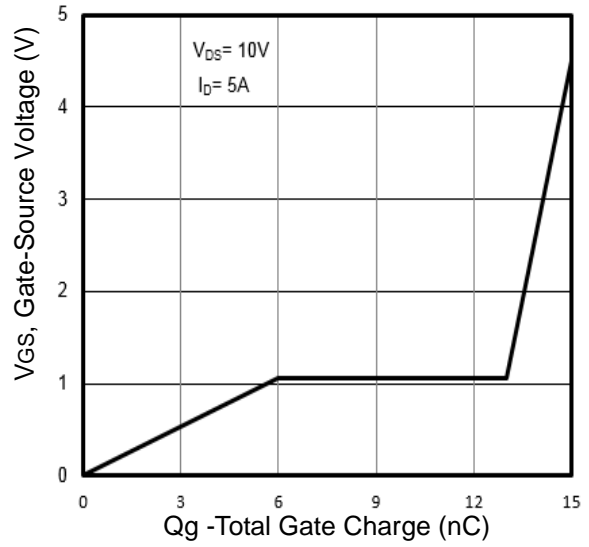


Fig8. Typical Gate Charge Vs. Gate-Source

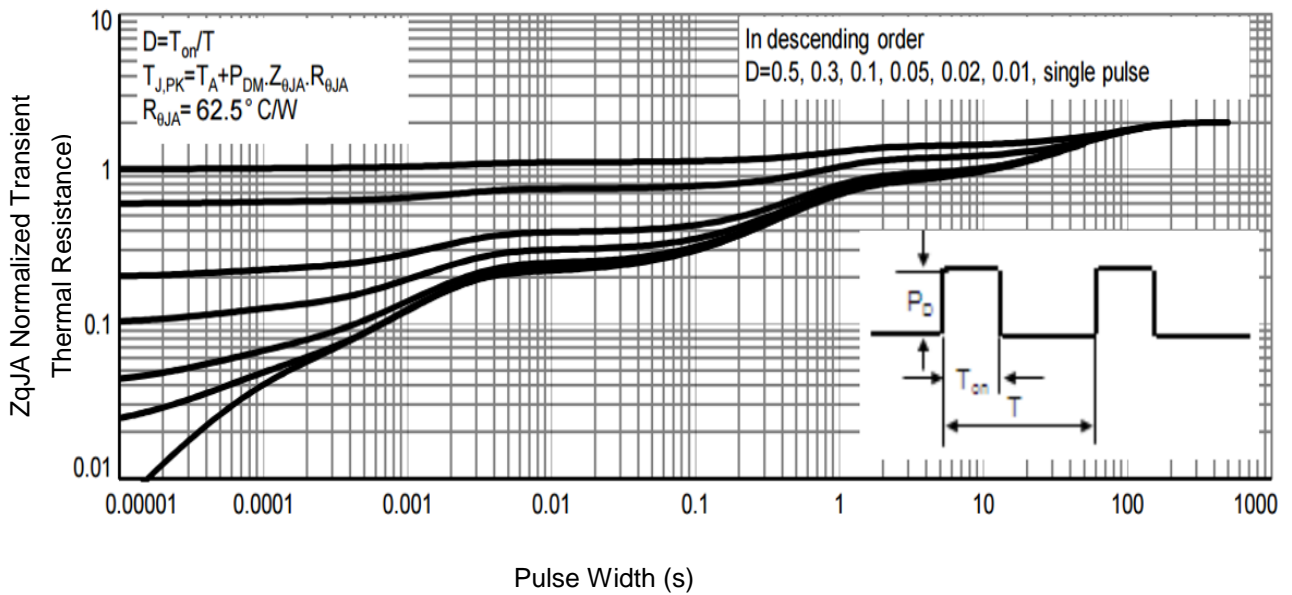


Fig9. Normalized Maximum Transient Thermal Impedance

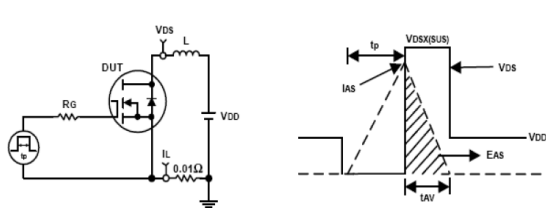


Fig10. Unclamped Inductive Test Circuit and waveforms

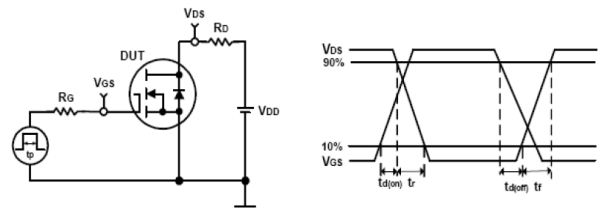
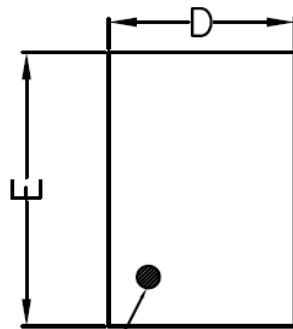


Fig11. Switching Time Test Circuit and waveforms

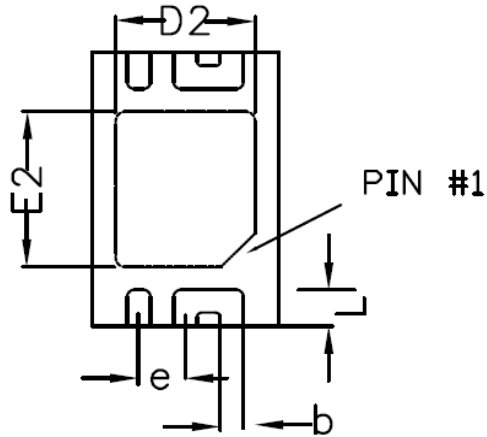


TDFN2x3-6L Package Outline Data

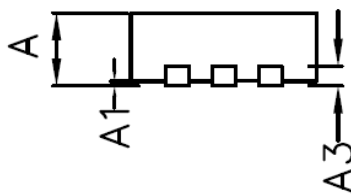


PIN 1 DOT
BY MARKING

TOP VIEW



BOTTOM VIEW



SIDE VIEW

DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.70	0.80	0.85	A1	0.00	--	0.05
A3	0.195	0.200	0.211	D	1.95	2.00	2.05
D2	1.45	1.50	1.55	E	2.95	3.00	3.05
E2	1.65	1.70	1.75	b	0.20	0.25	0.30
L	0.35	0.40	0.45	e	0.50 BSC		

Note:

1. Refer to JEDEC MO-229 variation W2030D-1.

Customer Service

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